

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4257995

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the TO CORRECT THE NAME OF THE THIRD ASSIGNOR previously recorded on Reel 040733 Frame 0810. Assignor(s) hereby confirms the THE UPDATED ASSIGNMENT SUBMITTED HEREWITH SUPPORTS THE REQUESTED CHANGE.
CONVEYING PARTY DATA	
Name	Execution Date
CHIA-MING HSU	11/30/2016
CHIH-PIN TSAO	11/30/2016
JYH-HUEI CHEN	12/01/2016
KUANG-YUAN HSU	12/06/2016
PEI-YU CHOU	11/30/2016
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15378574
CORRESPONDENCE DATA	
Fax Number:	(202)756-8087
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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Address Line 2:	500 NORTH CAPITOL STREET, N.W.
Address Line 4:	WASHINGTON, D.C. 20001
ATTORNEY DOCKET NUMBER:	095714-0144
NAME OF SUBMITTER:	TAKASHI SAITO
SIGNATURE:	/TAKASHI SAITO/

PATENT

DATE SIGNED:	02/03/2017
Total Attachments: 7 source=REQUESTFORCORRECTEDRECORDATION#page1.tif source=REQUESTFORCORRECTEDRECORDATION#page2.tif source=REQUESTFORCORRECTEDRECORDATION#page3.tif source=REQUESTFORCORRECTEDRECORDATION#page4.tif source=REQUESTFORCORRECTEDRECORDATION#page5.tif source=REQUESTFORCORRECTEDRECORDATION#page6.tif source=REQUESTFORCORRECTEDRECORDATION#page7.tif	



UNITED STATES PATENT AND TRADEMARK OFFICE

UNDER SECRETARY OF COMMERCE FOR INTELLECTUAL PROPERTY AND
DIRECTOR OF THE UNITED STATES PATENT AND TRADEMARK OFFICE

DECEMBER 22, 2016

PTAS

MCDERMOTT WILL & EMERY LLP
THE MCDERMOTT BUILDING
500 NORTH CAPITOL STREET, N.W.
WASHINGTON, DC 20001

504145198

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RECORDATION DATE: 12/14/2016

REEL/FRAME: 040733/0810
NUMBER OF PAGES: 5

BRIEF: ASSIGNMENT OF ASSIGNORS INTEREST (SEE DOCUMENT FOR DETAILS).

DOCKET NUMBER: 095714-0144

ASSIGNOR:

HSU, CHIA-MING

DOC DATE: 11/30/2016

ASSIGNOR:

TSAO, CHIH-PIN

DOC DATE: 11/30/2016

ASSIGNOR:

CHEN, ~~JHY-HUEI~~ JYH-HUEI

DOC DATE: 12/01/2016

ASSIGNOR:

HSU, KUANG-YUAN

DOC DATE: 12/06/2016

ASSIGNOR:

CHOU, PEI-YU

DOC DATE: 11/30/2016

ASSIGNEE:

TAIWAN SEMICONDUCTOR MANUFACTURING
CO., LTD.
NO. 8, LI-HSIN RD. 6
SCIENCE-BASED INDUSTRIAL PARK
HSINCHU, TAIWAN 300

APPLICATION NUMBER: 15378574

FILING DATE: 12/14/2016

PATENT NUMBER:

ISSUE DATE:

TITLE: SEMICONDUCTOR DEVICE AND A METHOD FOR FABRICATING THE SAME

ASSIGNMENT RECORDATION BRANCH

PUBLIC RECORDS DIVISION



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PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1

Stylesheet Version v1.2

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>CHIA-MING HSU</td><td>11/30/2016</td></tr><tr><td>CHIH-PIN TSAO</td><td>11/30/2016</td></tr><tr><td>JHY-HUEI-CHEN JYH-HUEI</td><td>12/01/2016</td></tr><tr><td>KUANG-YUAN HSU</td><td>12/06/2016</td></tr><tr><td>PEI-YU CHOU</td><td>11/30/2016</td></tr></tbody></table>		Name	Execution Date	CHIA-MING HSU	11/30/2016	CHIH-PIN TSAO	11/30/2016	JHY-HUEI-CHEN JYH-HUEI	12/01/2016	KUANG-YUAN HSU	12/06/2016	PEI-YU CHOU	11/30/2016
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Email:	ipdockeitmwe@mwe.com
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ATTORNEY DOCKET NUMBER:	095714-0144
NAME OF SUBMITTER:	TAKASHI SAITO
Signature:	/TAKASHI SAITO/
Date:	12/14/2016
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 3 source=DECLARATIONASSIGNMENT#page1.tif source=DECLARATIONASSIGNMENT#page2.tif source=DECLARATIONASSIGNMENT#page3.tif	
RECEIPT INFORMATION	
EPAS ID:	PAT4185044
Receipt Date:	12/14/2016

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COMBINED DECLARATION AND ASSIGNMENT FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

I believe I am the original or an original joint inventor of a claimed invention in the application for which a patent is sought on the invention entitled:

A SEMICONDUCTOR DEVICE AND A METHOD FOR FABRICATING THE SAME

which application is:

- ☒ attached, or
- ☐ United States application number or PCT international application number
_____ filed on _____.

The above-identified application was made or authorized to be made by me.

In the event that the filing date and/or application number are not entered above at the time I execute this document, and if such information is deemed necessary, I hereby authorize and request the registered practitioners of **McDermott Will & Emery LLP**, associated with the Customer Number **20277**, to insert above the filing date and/or application number of the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I hereby assign to

TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsinchu, Taiwan 300

(hereinafter designated as the Assignee), the entire (100%) right, title and interest for the United States as defined in 35 USC §100, in the invention described in the application identified in this document.

I hereby confirm any prior assignment to Assignee, and to the extent that I have not already done so, agree to assign, and hereby do, sell, assign and transfer unto Assignee and its successors in interest, the full and exclusive right, title and interest in the United States of America and throughout the world, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, to the inventions as described in the aforesaid application, to the aforesaid application itself, and all divisions, continuations, continuations-in-part, or other applications claiming priority directly or indirectly from the aforesaid application, and any United States or foreign Letters Patent, utility model, or other similar rights which may be granted thereon, including reissues, reexaminations and extensions thereof, and all copyright rights throughout the world in the aforesaid application and the subject matter disclosed therein, these rights, title and interest to be held and enjoyed by Assignee to the full end of the term for which the Letters Patent, utility model, or other similar rights, are granted and any extensions thereof as fully and entirely as the same would have been held by the undersigned had this assignment and sale not been made, and the right to sue for, and recover for past infringements of, or liabilities for, any of the rights relating to any of the applications, patents, utility models, or other similar rights, resulting therefrom, and the copyright rights;

I hereby covenant and agree to execute all instruments or documents required or requested for the making and prosecution of any applications of any type for patent, utility model, or other similar rights, and for copyright, in the United States and in all foreign countries including, but not limited to, any provisional, continuation, continuation-in-part, divisional, renewal or substitute thereof, and as to letters patent any reissue, re-examination, or extension thereof, and for litigation regarding, or for the purpose of protecting title and to the said invention, the United States application for patent, or Letters Patent therefor, and to testify in support thereof, for the benefit of Assignee without further or other compensation than that above set forth;

I hereby covenant that no assignment, sale, license, agreement or encumbrance has been or will be entered into which would conflict with this Assignment.

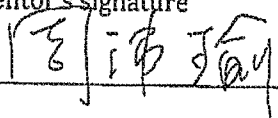
Attorney Docket No. 095714-0144 (P20151397US00)

Legal name of inventor Chia-Ming HSU	
Inventor's signature Chia-Ming Hsu	Date 2016/11/30

Legal name of inventor Chih-Pin TSAO	
Inventor's signature Chih-Pin Tsao	Date 2016.11.30

Legal name of inventor Jyh-Huei CHEN <u>Jyh-Huei</u> J.C. 2017/1/26	
Inventor's signature Jyh-Huei Chen	Date 2016/12/01

Legal name of inventor Kuang-Yuan HSU	
Inventor's signature Kuang-Yuan Hsu	Date 2016/12/06

Legal name of inventor Pei-Yu CHOU	
Inventor's signature  Pei-Yu CHOU	Date 2016.11.30